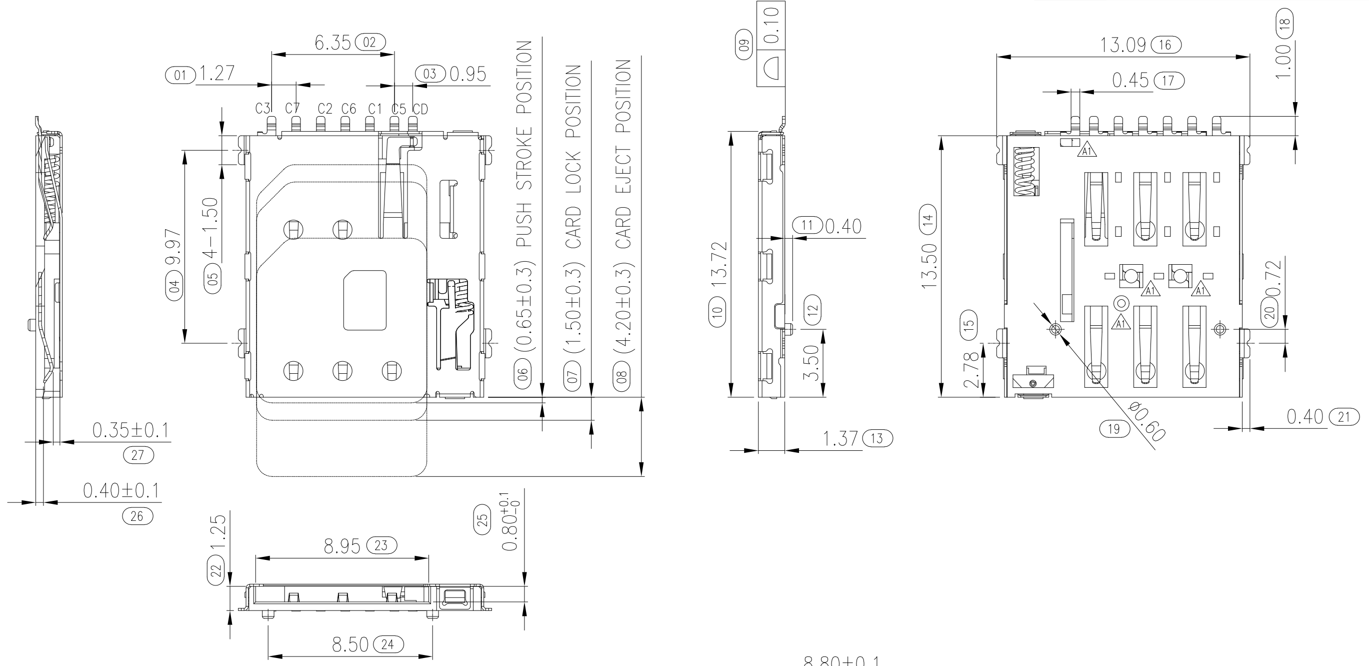
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2020/02/11	Phebe Su
A1			Initial	2020/12/14	Hanson



Specification:

MATERIAL:

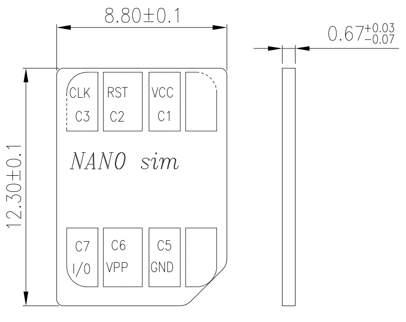
Insulator: High Temperature Thermoplastic, UL 94V-0. Black
Contact: Copper Alloy
SHELL: STANLESS STEEL

PLATING:

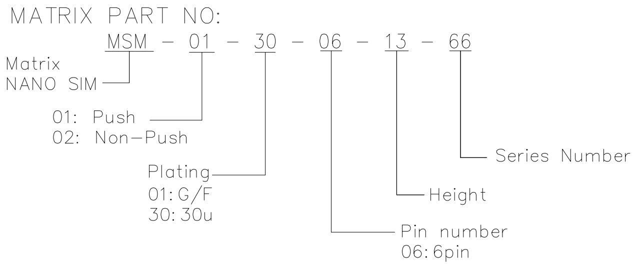
Contact Area: Au 30u″.
Solder Area: Gold flash plated. Under plate: nickel.
Shell: Nickel plated over all.
Solder Area: Gold flash.

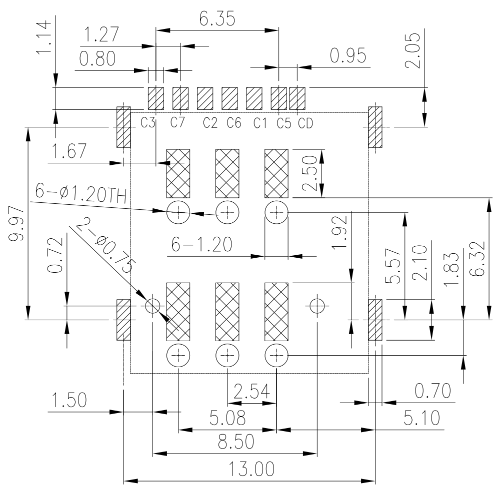
Electrical:

Current Rating :0.5A max.
Voltage Rating :30V
Ambient Temperature Range :-40° C~+85° C
Storage Temperature Range :-40° C~+85° C
Humidity: 80% R.H. Max.
Contact Resistance:50mΩmax.
Insulation Resistance:1000MΩ MIN 500V DC
Mating Cycles:5,000 Insertions
Solder ability:260+0/-5° C.30±10s.



NANO SIM CARD



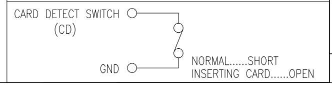


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

▨ PAD
▩ KEEP OUT AREA

SIM pin assignment	
PIN#	Name
C1	VCC供
C2	RST重置
C3	CLK
C5	GND接地
C6	VPP程序
C7	I/0 入 出

CRICUIT DIAGRAM FOR CARD DETECT SWITCH



Matrix Electronics Co.,Ltd

TOLERANCE:
X.
X.X ±0.30
X.XX ±0.20
X.XXX ±0.10
ANGLE: ±3°

UNIT: mm [inch]
SCALE:1:1
SIZE:A4

DESIGN BY : Hanson Huang	DATE : 2020/12/14	PART NAME: NANO-SIM PUSH/PUSH 1.35H	
CHECKED BY: Vicky Hsieh	DATE : 2020/12/14	PART NO.	MSM-01-30-06-13-66
APPROVED BY1: Richard Hsieh	DATE : 2020/12/14	MOLD NO.	NA
APPROVED BY2: Richard Hsieh	DATE : 2020/12/14	DRAW NO.	
		SHEET NO.	1 OF 1